

Crystal LTD TM SPEC Form www.crystaltherm.com

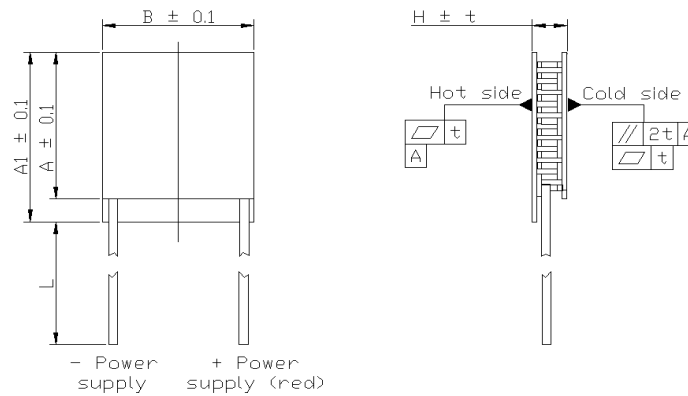
Customer

PO#
PO date

Thermoelectric module (TM) specification

PO position #	TM	Internal Solder Melting Temp, C	Max operating temperature, °C		Parameters in vacuum at hot side temperature 25 °C				Rac at 25 °C		Ceramic size, mm		TM Height		Wire			Sealing
			short peak	continuous operation	I _{max} , A	U _{max} , V	Q _{max} , W	dT _{max} , K	R _{ac} , Ohm	Tolerance ±, %	A/A1	B	Height, mm	Tolerance t, ± mm	S, mm ²	Length, mm	Tolerance ±, mm	
1	S-241-07-15	138	130	115	1.5	30.7	28.5	74.5	15.51	10	30/30	30	2.90	0.2	0.12	100	1	
															MGTF (teflon)			
															or			
															30AWG solid tinned uninsulated			

Clamping force: 14.3 - 28.5 kg



Max dT is reduced by 2-3K for silicon sealed and 1-2K for epoxy sealed versions.



U(dT) at $T_{hot}=298K$

